application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulation, §1.56(a) which occurred between the filing date of the prior application and the PCT international filing date of this application:

(Application Serial No.) (Filing Date)

(Status) (patented, pending, abandoned)

I hereby appoint Holly D. Kozlowski, Registration No. 30,468; Ronald J. Snyder, Registration No. 31,062; James D. Liles, Registration No. 28,320; Lynda E. Roesch, Registration No. 29,696; Phillip A. Rotman II, Registration No. 38,290; Martin J. Miller, Registration No. 35,953; Victor C. Moreno, Registration No. 40,732; Jackie A. Zurcher, Registration No. 42,251; John V. Harmeyer, Registration No. 41,815; Scott N. Barker, Registration No. 42,292; and Geoffrey L. Oberhaus, Registration No. 42,955, c/o Dinsmore & Shohl, 1900 Chemed Center, 255 East Fifth Street, Cincinnati, Ohio 45202 (513) 977-8200, my attorneys, with full power in each of them, of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

The undersigned hereby authorizes the above-named U.S. attorneys to accept and follow as to any action to be taken in the Patent and instructions from Shigeaki Nishikawa Trademark Office regarding this application without direct communication between the undersigned and the aforenamed U.S. attorneys. In the event of a change in the firm or persons from whom instructions may be taken, the aforenamed U.S. attorneys will be so notified in writing by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Junji KODEMURA

Kodemura Junfi Inventor's signature

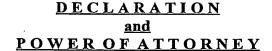
December 22, 1999

Date

Kanagawa 210-0863 Japan Residence:

Citizenship: Japanese

c/o Research & Development Center, Nippon Zeon Co., Ltd., Post Office Address: 2-1, Yako 1-chome, Kawasaki-ku, Kawasaki-shi, Kanagawa 210-0863 Japan



## **U.S. NATIONAL PHASE OF INTERNATIONAL APPLICATION**

I believe I am the original, first and sole inventor (if only one name is listed below) or an

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

riginal, first and joint inventor (if plural names are listed below) of the subject matter which is
laimed and for which a patent is sought on the invention entitled
ADHESIVE FOR SEMICONDUCTOR PART
ne specification of which was filed as International Application No. PCT/JP98/03033
n_July 6, 1998 ,
[ ] and was amended under Article 19 on
(if applicable)
[X] and was amended under Article 34 on May 21, 1999.
(if applicable)
and was assigned U.S. Application Serial No.
and was amended on .
(if applicable)
(ii application)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)					
			Priority Claimed		
Number	Country	Day/Month/Year Filed	Yes	No	
195066/ 1997	Japan	04/07/1997	Х		

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this